

Abstract of the Disclosure:

A planar electronic component has a functional layer with an optoelectronic or a circuit configuration between a substrate layer and a covering layer. A sealing frame or sealing ring is
5 disposed between the substrate layer and the covering layer and connected to them by an integral joint surrounding the functional layer. The seal very largely protects the functional layer against hazardous external influences, in particular against moisture and oxygen. A mechanical
10 connector, whose adhesive characteristics are matched to the materials of the covering layer and of the substrate, is provided in addition to the sealing ring. The connector fixes the substrate and covering layers mechanically with respect to one another, and may reduce the risk of partial or complete
15 detachment in the event of deformation of the electronic component, in particular as a result of thermal expansion and/or mechanical loading.